Layer Stack Up Detail for: PR2192E1.PcbDoc

Layer Name	Border Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil				
			16.4mil	FR-4 High TG	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

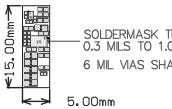
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 5.5 MIL
MIN. VIA PAD SIZE: 10 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 20 MIL (0.53mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



SOLDERMASK THICKNESS MUST BE MAINTAINED FROM 0.3 MILS TO 1.0 MILS MAX IN THIS AREA
6 MIL VIAS SHALL BE PLATED CLOSED.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

Texas Instruments

PROJECT TITLE: TIDA-00318
DESIGNED FOR: Public Release
FILE NAME: TIDA-00318.PcbDoc

ENGINEER: Marco Hsieh
LAYOUT BY: Krypton Solutions/RS
SCALE: 0.70
ALTIUM DESIGNER VERSION: 10.0.0.27009

Layer Stack Up Detail for: PR2192E1.PcbDoc

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DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
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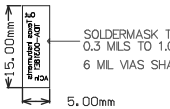
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



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ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-00318
DESIGNED FOR: Public Release
FILE NAME: TIDA-00318.PcbDoc

ENGINEER: Marco Hsieh
LAYOUT BY: Krypton Solutions/RS
SCALE: 0.70
ALTIUM DESIGNER VERSION: 10.0.0.27009

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